



20V P-CHANNEL ENHANCEMENT MODE MOSFET POWERDI

Product Summary

| BV _{DSS} | R _{DS(ON)} | I _D T _C = +25°C |
|-------------------|---|--|
| | $1.9 m\Omega @ V_{GS} = -10V$ | -60A |
| -20V | $2.4 m\Omega$ @ $V_{GS} = -4.5 V$ | -60A |
| | $3.8 \text{m}\Omega$ @ $V_{GS} = -2.5 \text{V}$ | -60A |

Description

This new generation P-Channel Enhancement Mode MOSFET is designed to minimize $R_{DS(ON)}$ and yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

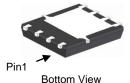
Applications

Switch

PowerDI5060-8 (Type K)





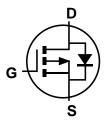


Features

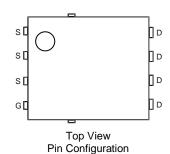
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: PowerDI5060-8 (Type K)
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe;
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)



Internal Schematic



Ordering Information (Note 4)

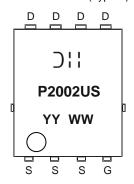
| Part Number | Case | Packaging | | |
|---------------|------------------------|---------------------|--|--|
| DMP2002UPS-13 | PowerDI5060-8 (Type K) | 2,500 / Tape & Reel | | |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

PowerDI5060-8 (Type K)



☐ I = Manufacturer's Marking
P2002US = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | | |
|---|--------------------------|--|----------------|--------------|---|
| Drain-Source Voltage | V _{DSS} | -20 | V | | |
| Gate-Source Voltage | V _{GSS} | ±12 | V | | |
| Continuous Dunis Courset V 40V (Note 5) | Steady State (Note 8) | $T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$ | | -60 -60 | А |
| Continuous Drain Current, V _{GS} = -10V (Note 5) | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | -42 -33.5 | А |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | I _{DM} | -100 | А | | |
| Continuous Body Diode Forward Current (Note 5) | Steady State (Note 8) | T _C = +25°C | Is | -60 | А |
| , | t<10s | $T_A = +25$ °C | .5 | -5.6 | Α |
| Pulsed Body Diode Forward Current (10µs pulse, duty cyc | I _{SM} | -100 | А | | |
| Avalanche Current, L = 0.1mH | I _{AS} | -37 | А | | |
| Avalanche Energy, L = 0.1mH | E _{AS} | 69.8 | mJ | | |

Thermal Characteristics

| Characteristic | Symbol | Value | Units | |
|--|--------------|-----------------------------------|-------------|------|
| Total Davier Dissination (Note 5) | Steady State | Б | 2.3 | W |
| Total Power Dissipation (Note 5) | t<10s | P_D | 6.25 | |
| Thermal Desistance Junction to Ambient (Note 5) | Steady State | Ъ | 55 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s | $R_{\theta JA}$ | 20 | |
| Total Power Dissipation (Note 5) | Steady State | P _D | 104 | W |
| Thermal Resistance, Junction to Case (Note 5) | | R _{0JC} | 0.9 | °C/W |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

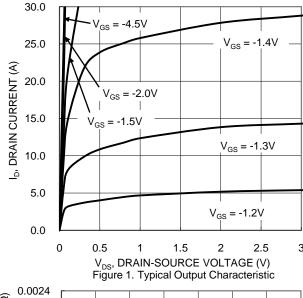
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|---|---------------------|------|-------|------|------|---|--|
| OFF CHARACTERISTICS (Note 6) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -20 | _ | _ | V | V _{GS} = 0V, I _D = -250μA | |
| Zero Gate Voltage Drain Current | IDSS | - | _ | -1 | μA | V _{DS} = -20V, V _{GS} = 0V | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 12V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 6) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -0.5 | 1 | -1.4 | V | $V_{DS} = V_{GS}$, $I_D = -250\mu A$ | |
| | | _ | 1.3 | 1.9 | mΩ | V _{GS} = -10V, I _D = -25A | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 1.5 | 2.4 | | $V_{GS} = -4.5V, I_D = -20A$ | |
| | | _ | 2 | 3.8 | | $V_{GS} = -2.5V, I_D = -15A$ | |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | | |
| Input Capacitance | C _{iss} | | 12826 | _ | | | |
| Output Capacitance | Coss | | 2547 | _ | pF | $V_{DS} = -10V$, $V_{GS} = 0V$ f = 1MHz | |
| Reverse Transfer Capacitance | C _{rss} | | 1924 | _ | | 1 - 11411 12 | |
| Gate Resistance | R _G | 0.9 | 4.2 | 6.6 | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge (V _{GS} = -10V) | Q_g | | 476 | 585 | | V _{DS} = -10V, I _D = -20A | |
| Total Gate Charge (V _{GS} = -4.5V) | Qg | | 228 | 282 | nC | | |
| Gate-Source Charge | Q _{gs} | | 24.8 | _ | 110 | | |
| Gate-Drain Charge | Q_{gd} | | 61.9 | _ | | | |
| Turn-On Delay Time | t _{D(ON)} | | 14.2 | 28 | | $V_{DD} = -10V, V_{GEN} = -4.5V,$ $R_{GEN} = 1\Omega, I_D = -10A$ | |
| Turn-On Rise Time | t _R | | 35.4 | 70 | no | | |
| Turn-Off Delay Time | t _{D(OFF)} | | 361 | 578 | ns | | |
| Turn-Off Fall Time | t _F | | 224 | 358 | | | |
| BODY DIODE CHARACTERISTICS | | | | | | | |
| Continuous Body Diode Forward Current (Notes 5 & 8) | Is | - | _ | -60 | Α | T _C = +25°C | |
| Diode Forward Voltage | V_{SD} | - | -0.58 | -1.1 | V | $V_{GS} = 0V, I_{S} = -5A$ | |
| Reverse Recovery Time (Note 7) | t _{RR} | _ | 137 | 219 | ns | | |
| Reverse Recovery Charge (Note 7) | Q _{RR} | _ | 221 | 332 | nC | 1 10 \ d:/dt 100 \/ | |
| Reverse Recovery Fall Time (Note 7) | t _A | _ | 39 | _ | no | $I_F = -10A$, di/dt = 100A/ μ s | |
| Reverse Recovery Raise Time (Note 7) | t _B | _ | 98 | _ | ns | | |

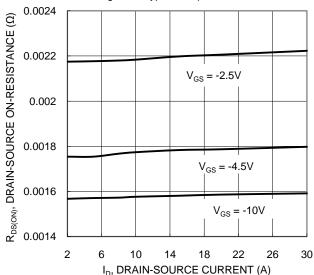
5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

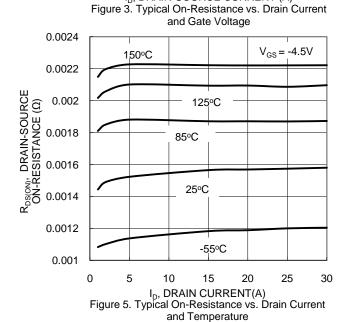
Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

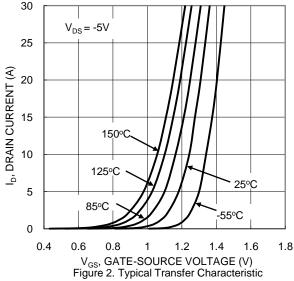
^{8.} Package limited.

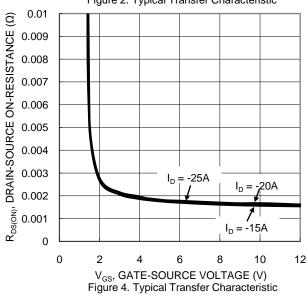


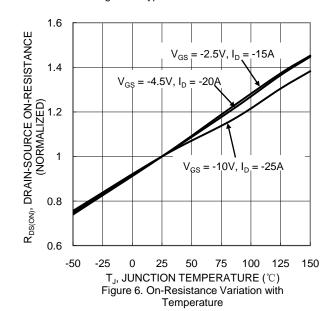




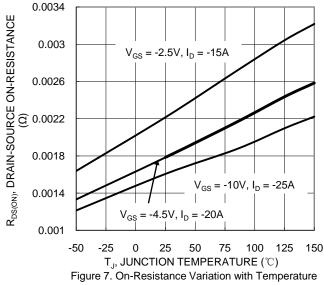


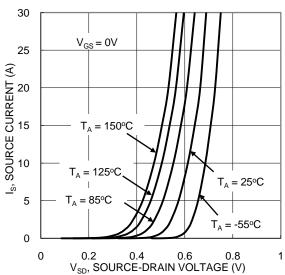


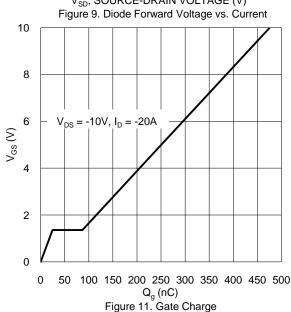


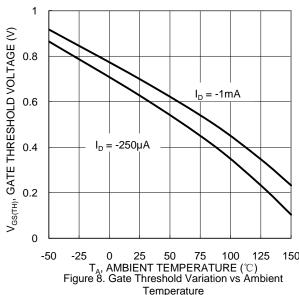


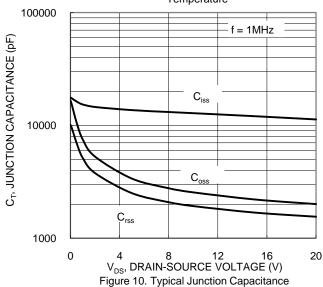


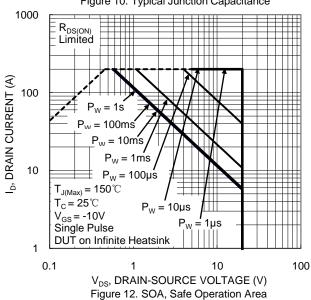














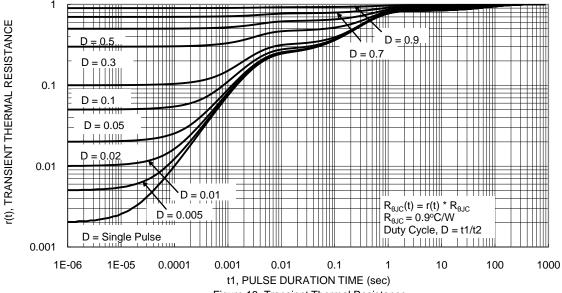


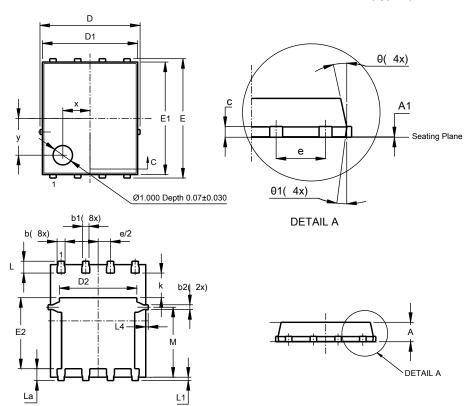
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type K)

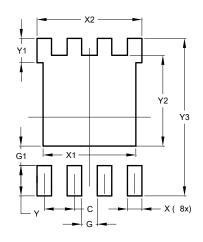


| PowerDI5060-8 (Type K) | | | | | |
|---------------------------|-------|---------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 0.90 | 1.10 | 1.00 | | |
| A1 | 0 | 0.05 | 0.02 | | |
| b | 0.33 | 0.51 | 0.41 | | |
| b1 | 0.300 | 0.366 | 0.333 | | |
| b2 | 0.20 | 0.35 | 0.25 | | |
| С | 0.23 | 0.33 | 0.277 | | |
| D | 5 | .15 BS0 | 3 | | |
| D1 | 4.85 | 4.95 | 4.90 | | |
| D2 | - | - | 3.98 | | |
| Е | 6 | .15 BS0 | | | |
| E1 | 5.75 | 5.85 | 5.80 | | |
| E2 | 3.56 | 3.725 | 3.66 | | |
| Е | 1 | .27BSC | ; | | |
| k | - | - | 1.27 | | |
| L | 0.51 | 0.71 | 0.61 | | |
| La | 0.51 | 0.675 | 0.61 | | |
| L1 | 0.05 | 0.20 | 0.175 | | |
| L4 | - | - | 0.125 | | |
| М | 3.50 | 3.71 | 3.605 | | |
| X | - | - | 1.400 | | |
| у | - | - | 1.900 | | |
| θ | 10° | 12° | 11° | | |
| θ1 | 6° | 8° | 7° | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type K)



| Dimensions | Value | | | |
|--------------|---------|--|--|--|
| Dilliensions | (in mm) | | | |
| С | 1.270 | | | |
| G | 0.660 | | | |
| G1 | 0.820 | | | |
| Х | 0.610 | | | |
| X1 | 3.910 | | | |
| X2 | 4.420 | | | |
| Υ | 1.270 | | | |
| Y1 | 1.020 | | | |
| Y2 | 3.810 | | | |
| Y3 | 6.610 | | | |



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